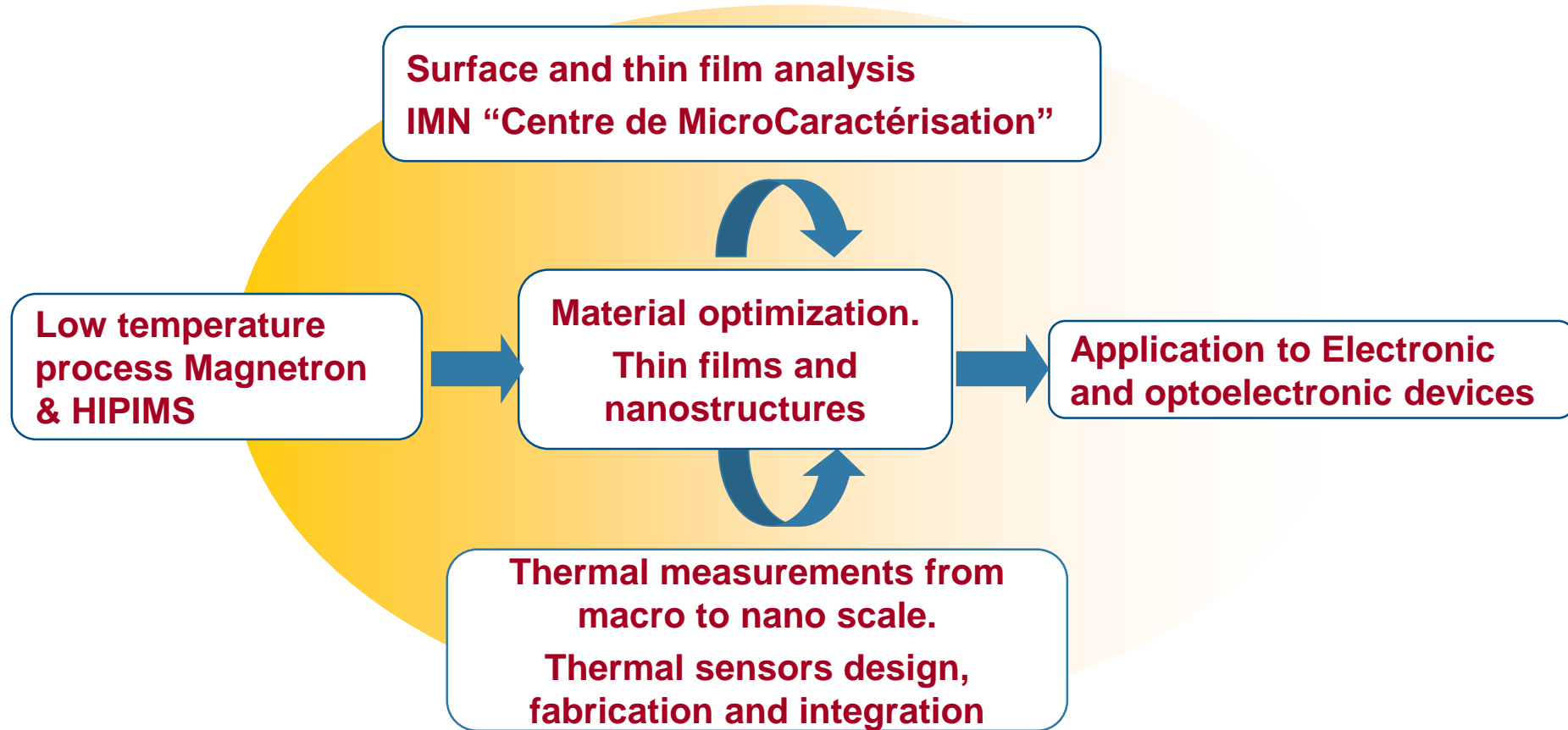


*Si/AlN Epiready substrates for Gallium Nitride growth :
Application to HEMT and LEDs devices*

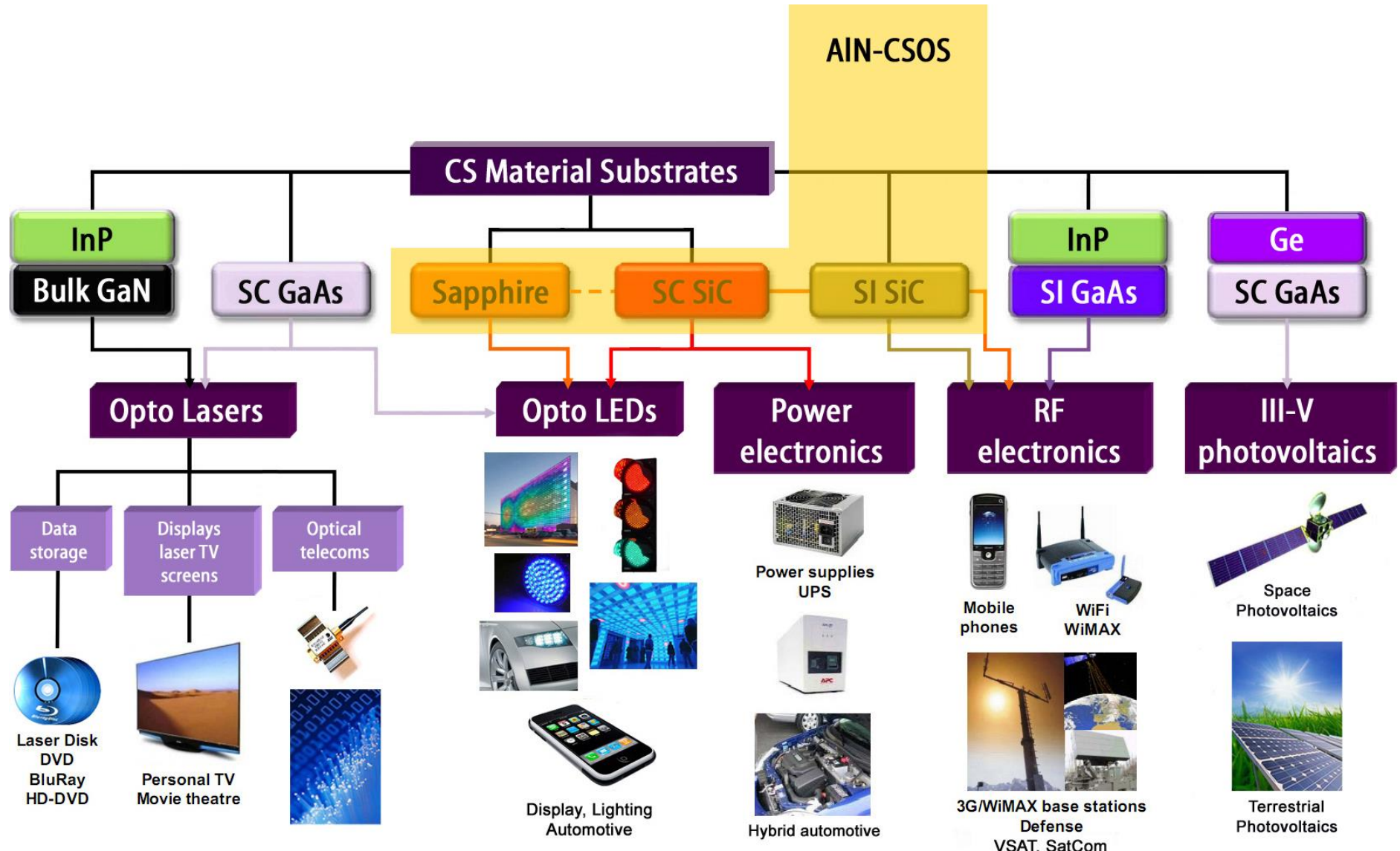
K. Ait Aissa, J. Camus, S. Bensalem, B. Belkerk, A. Achour, Q. Simon Y. Scudeller et A. Djouadi

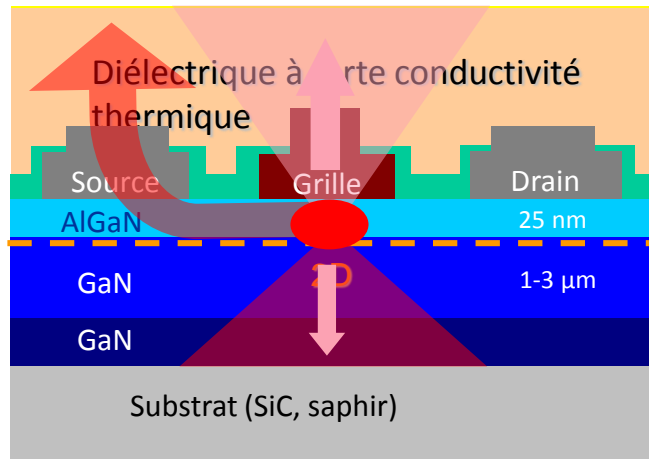
JOURNEE DES LABOS 2013, Angers



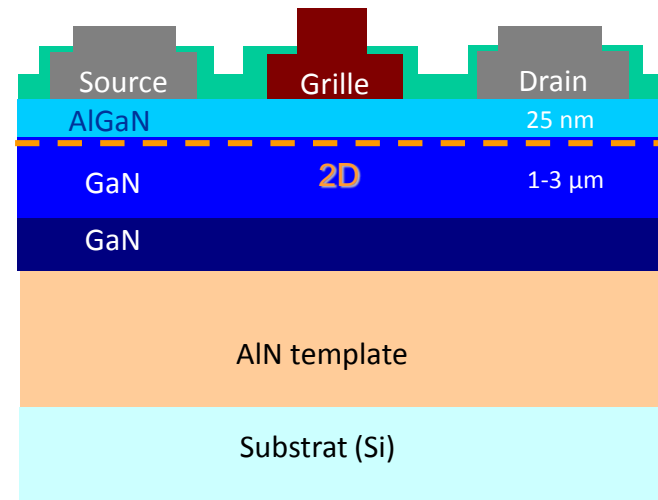
Control and mastery of process and material: Micro and NanoTechnology Applications

GaN material applications

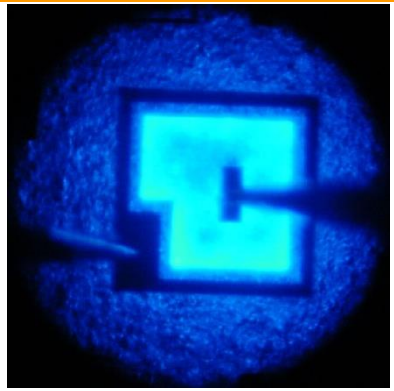
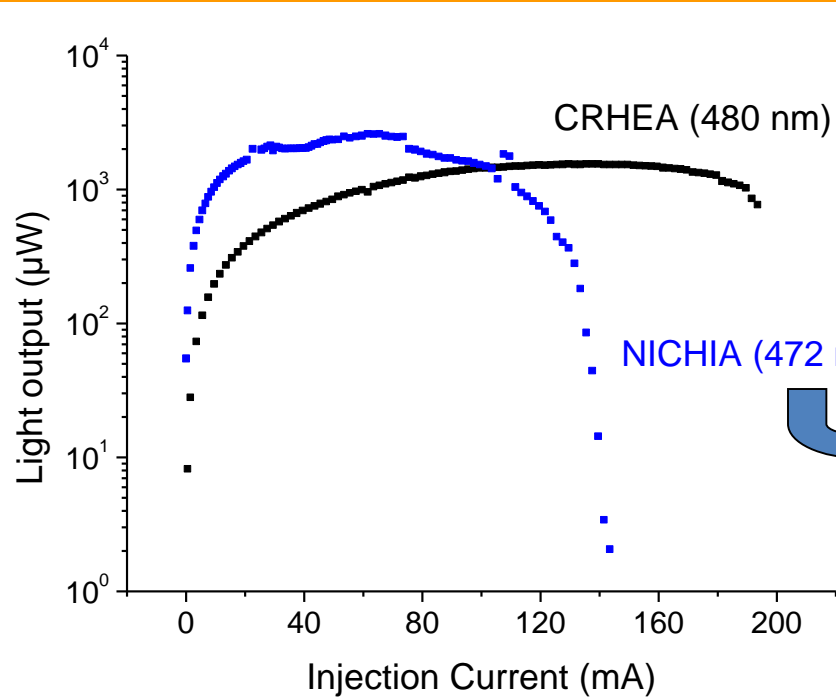




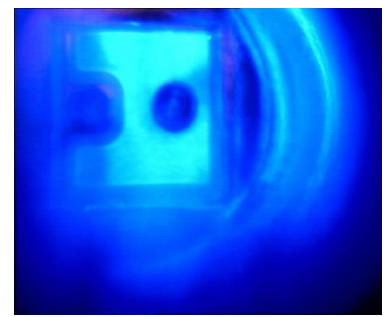
- 1^{ère} Couche de passivation (SiN/SiO₂)
- 2^{ème} couche de passivation diélectrique



Problematic

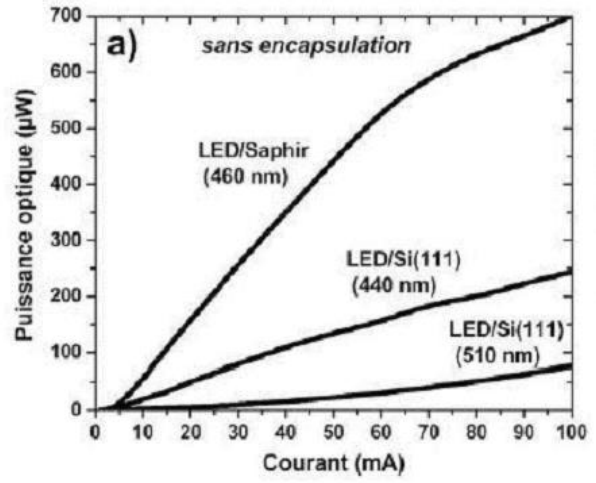


LED

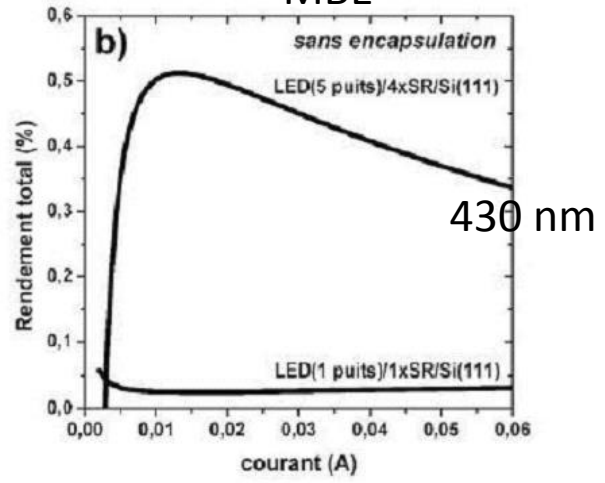


LED + epoxy dome

MOCVD



MBE



ANR CREATIVEPI Project

WP1

Management & Specifications

All partners

Task 1.1 IMN-CHREA-IMN
Project management

Task 1.2 IMN-CHREA-IMN
Specifications
Silicon handle wafer
Composite substrate
HEMT & LED demonstrators



WP2

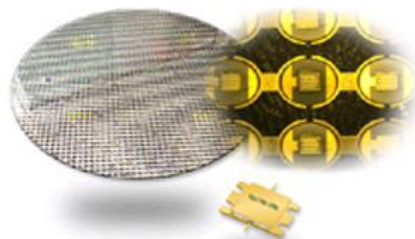
Composite substrate

All partners

Task 2.1 IMN
AlN/Si epitaxy by HIPIMS

Task 2.2 CRHEA
GaN regrowth by MOCVD & MBE

Task 2.3 IEMN-CRHEA-IMN
Characterization



WP4

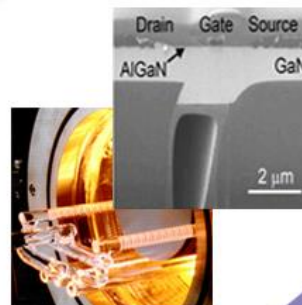
Evaluation & Dissemination

All partners

Task 4.1 CHREA-IEMN-IMN
Comparison / State-of-the-Art

Task 4.2 IMN-FIST
Dissemination of results

Task 4.3 IMN
Projection towards 6" scale-up



WP3

Demonstrators

All partners

Task 3.1 CHREA-IMN
GaN epitaxy by MOCVD & MBE

Task 3.2 IEMN-CRHEA
Technology demonstrators

Task 3.3 IEMN-CRHEA
Characterization demonstrators

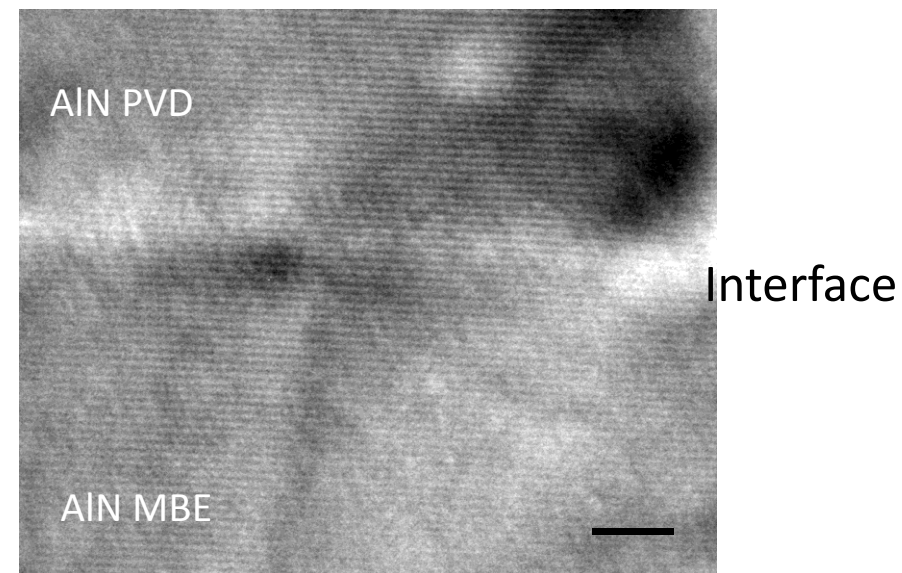
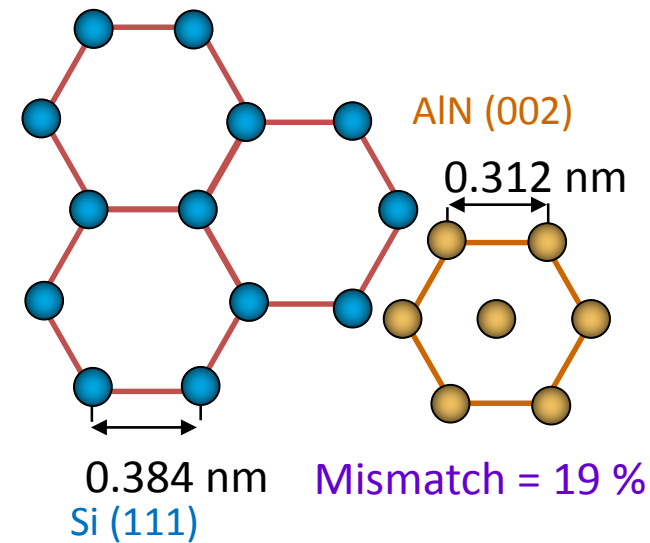
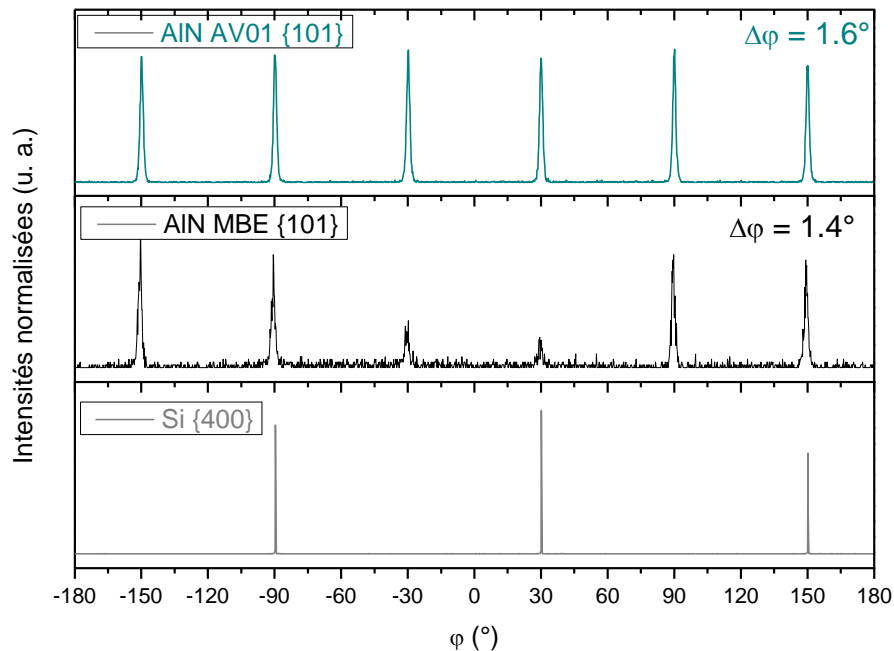
Epiready Substrate AlN(PVD)/AlN(MBE)/Si<111>

XRD: ϕ -scan

AlN PVD (IMN)

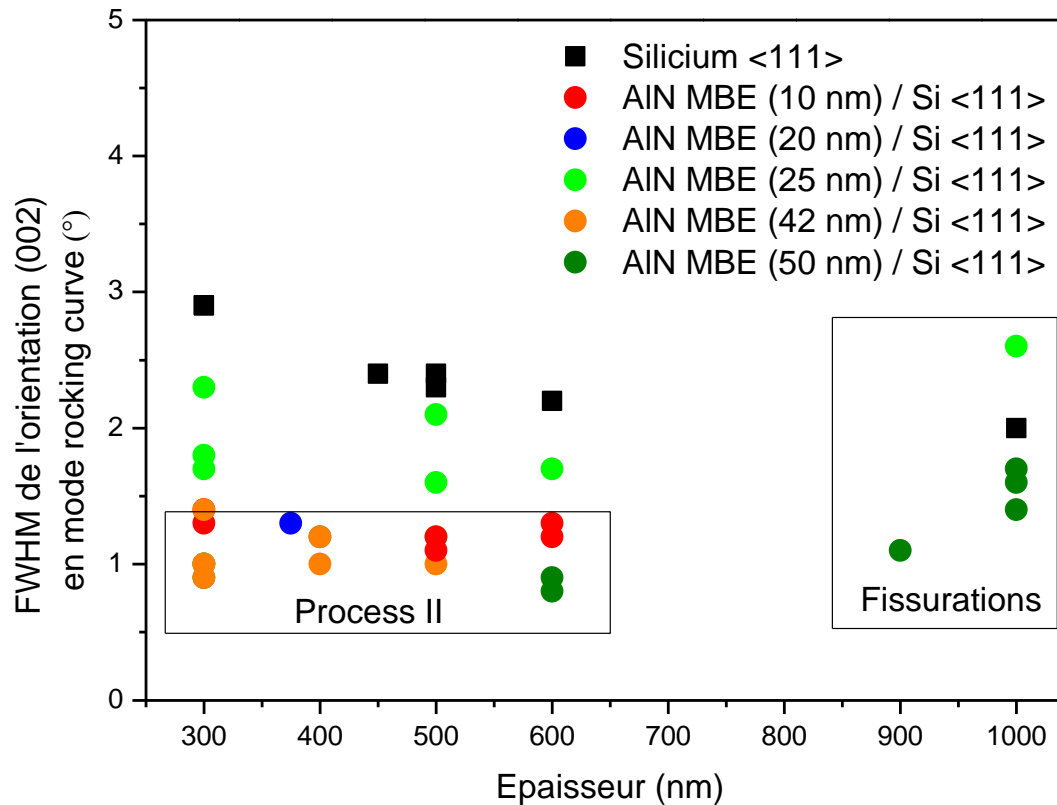
AlN MBE (CRHEA)

Si (111)



➤ Signature of epitaxial growth of AlN at low temperature

DRX: ω -scan (rocking-curve)



FWHM_{10 nm} = 2°

FWHM_{20 nm} = 1.2°

FWHM_{25 nm} = 1.1°

FWHM_{42 nm} = 0.9°

FWHM_{50 nm} = 0.9°

AIN PVD (IMN)

AIN MBE (CRHEA)

Si (111)

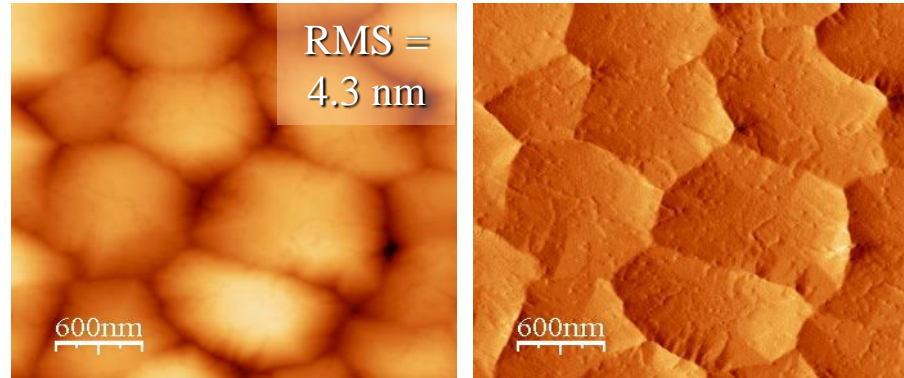
➤ Cracking of AlN MBE film with thickness > 150 – 200 nm

➤ AIN PVD films with no cracking up to 600 nm

➤ Stress control of the GaN upper film

Growth of epitaxial GaN films

Structure of HEMT device with AlN (PVD) Epiready substrate



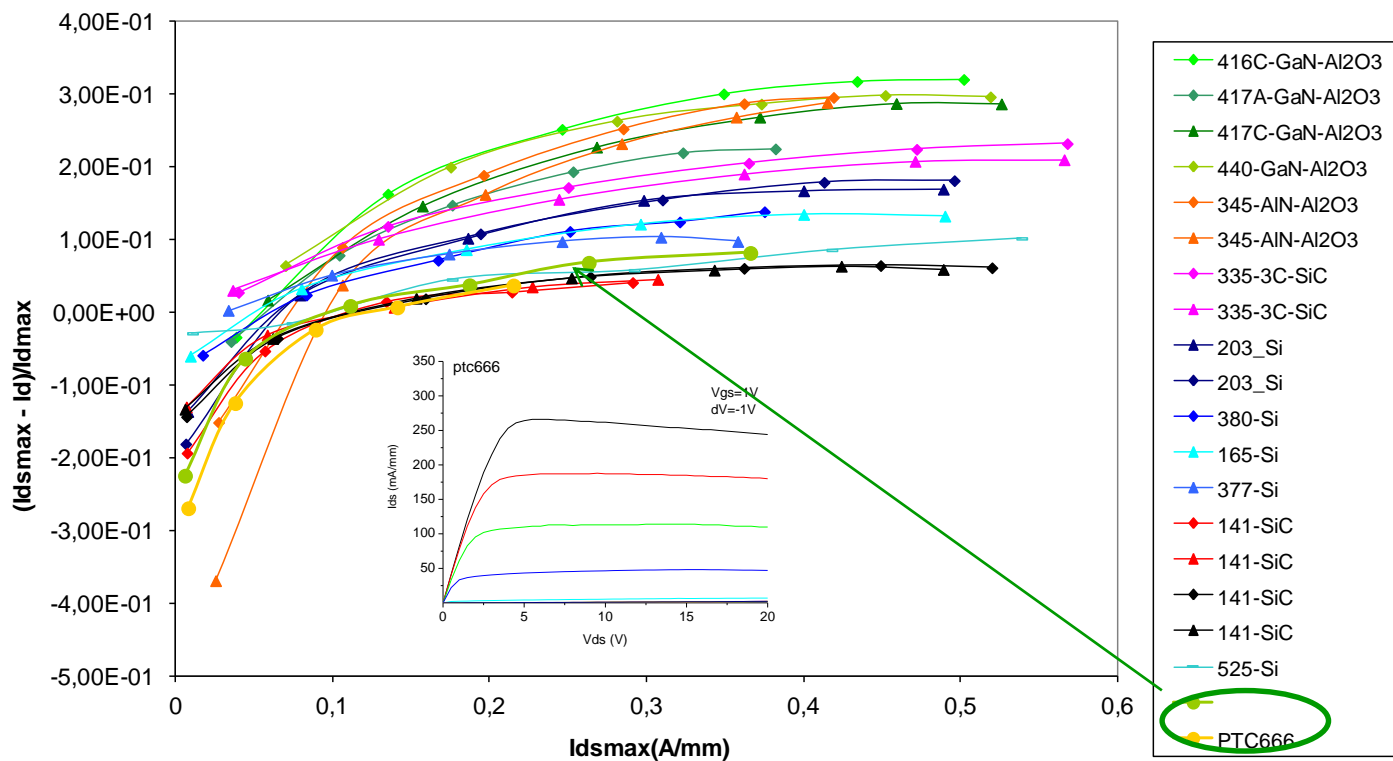
GaN epitaxial growth

Electrical Tests of GaN HEMT Device

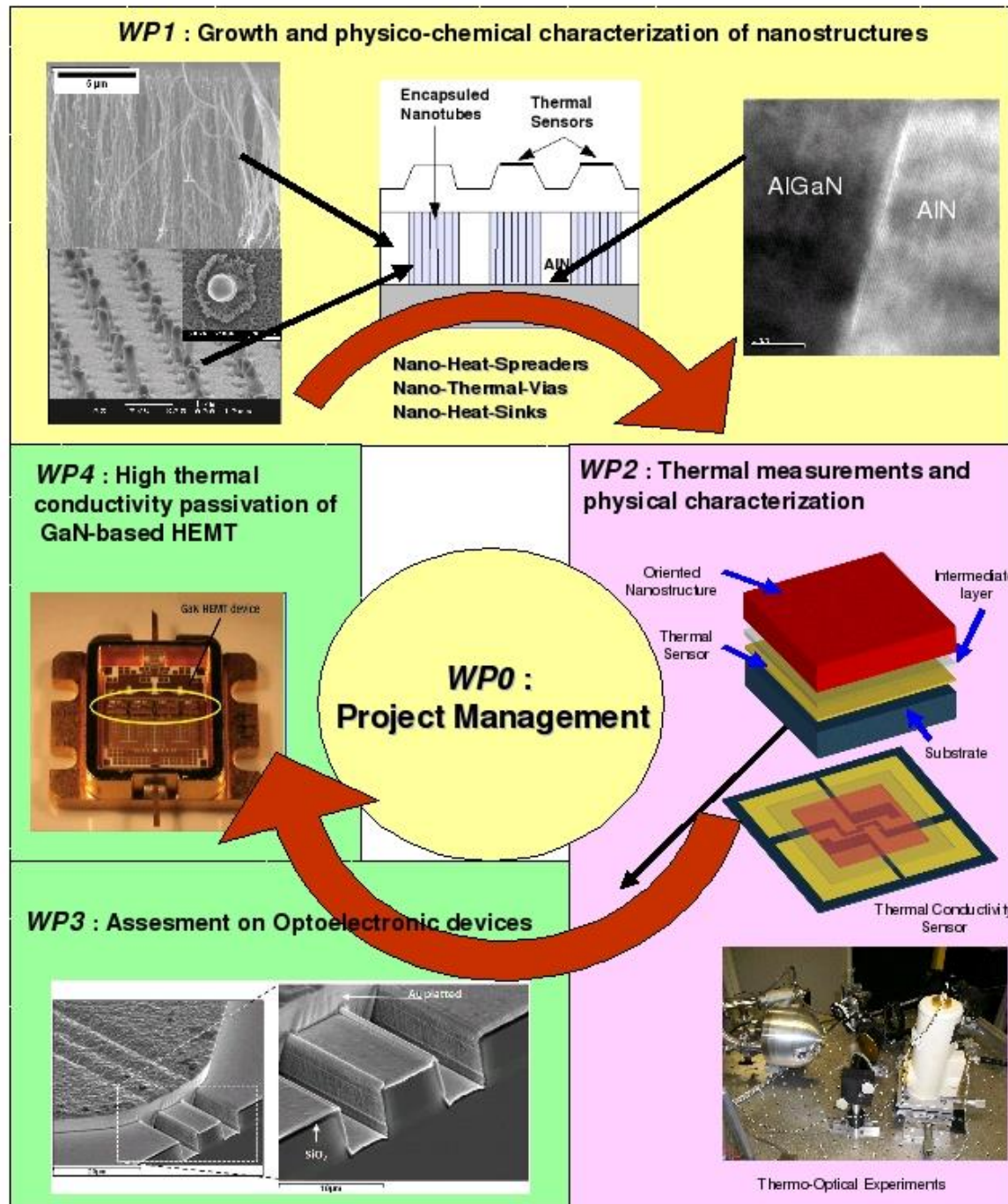
Comparaisons – collapse

$$COLLAPSE = \frac{Id_{knee} - Id_{20V}}{Id_{knee}}$$

Lg2-9um



NanoThermIC project



Consortium

IMN Univ. Nantes

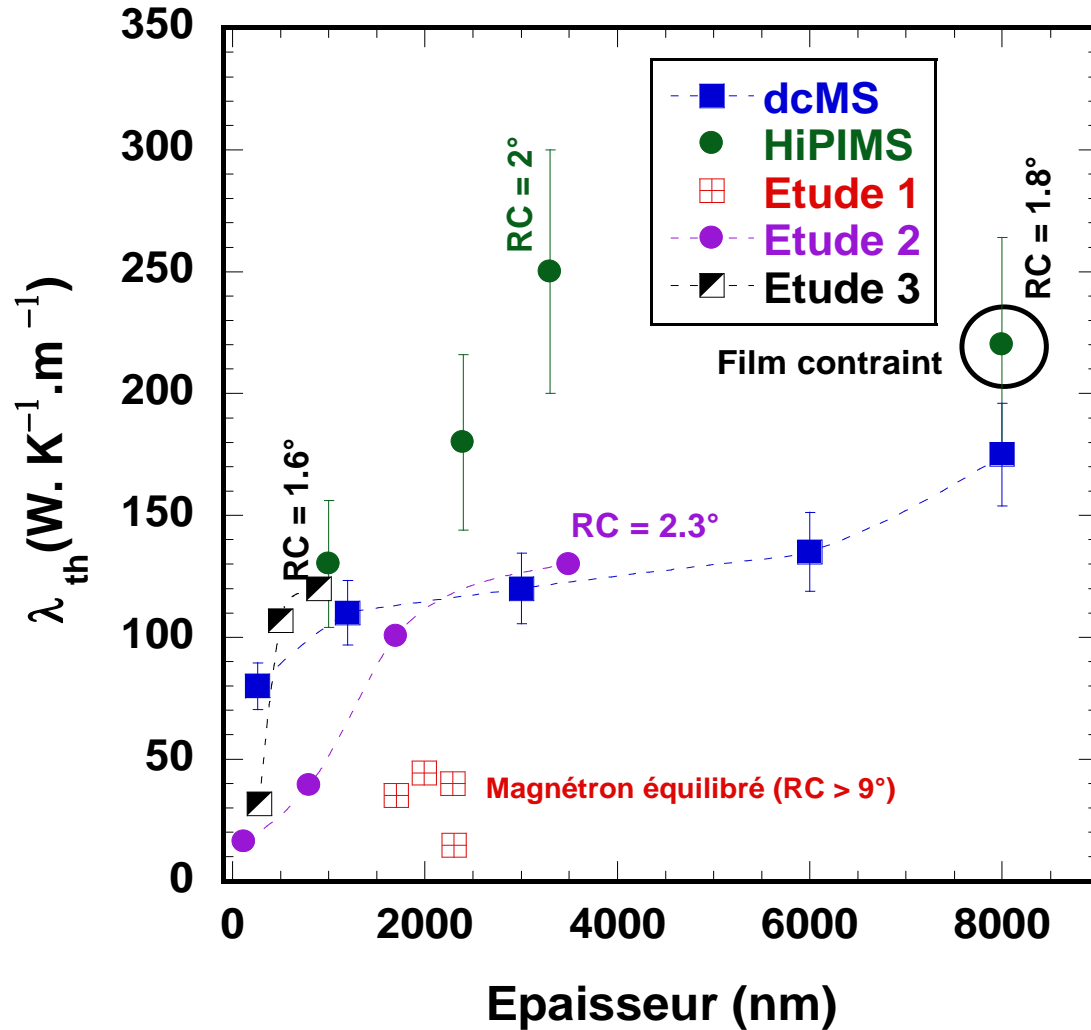
ATL, III-V Lab.

GREMI Polytech Orléans

LGMPA Polytech Nantes

ESPCI Paris

PDI, Univ. Berlin

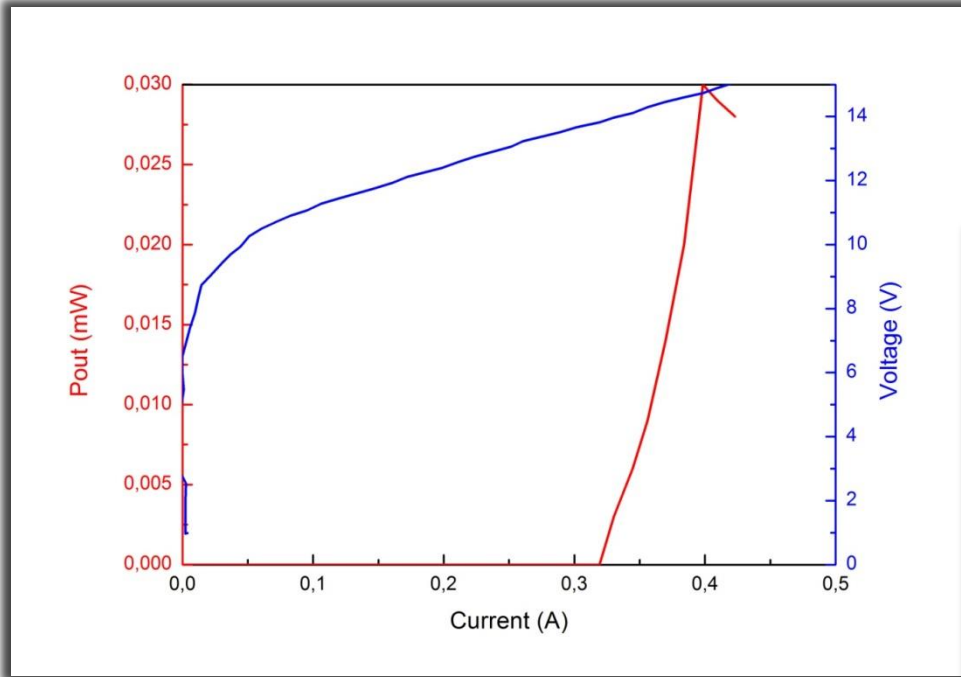


HiPIMS films exhibit thermal conductivity up to $250 \pm 50 \text{ W.K}^{-1}.\text{m}^{-1}$

Etude (1) et (2) : C. Duquenne, Thèse de doctorat, Université de Nantes (2008)

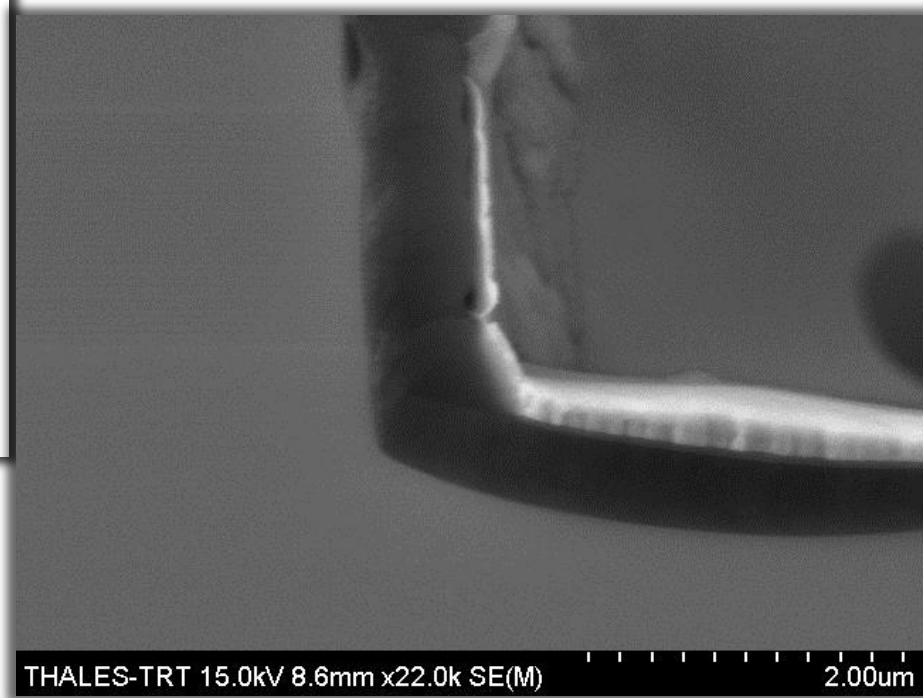
Etude (3): A. Soussou, Thèse de doctorat, Université de Nantes (2011).

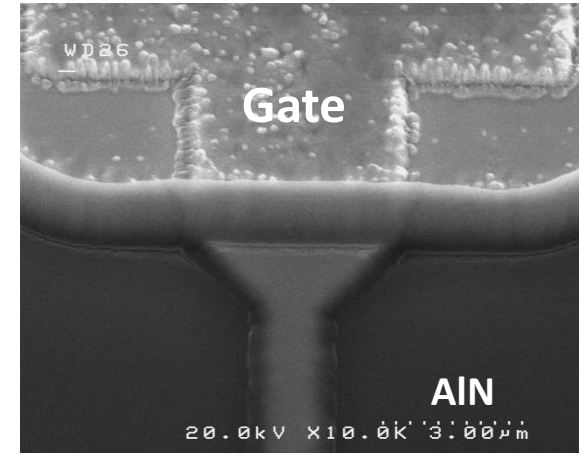
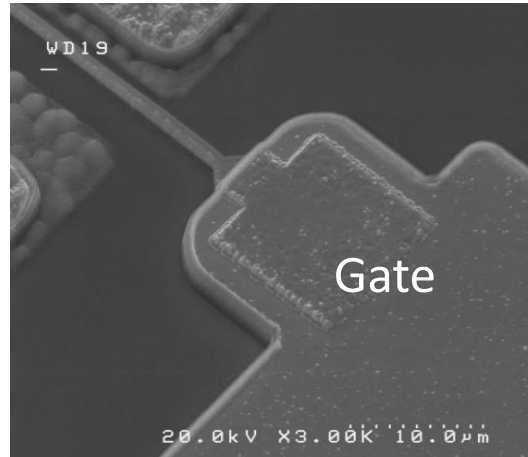
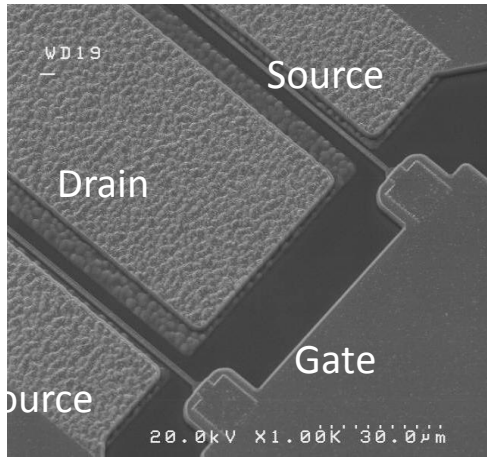
❖ QCL @3.9 μm



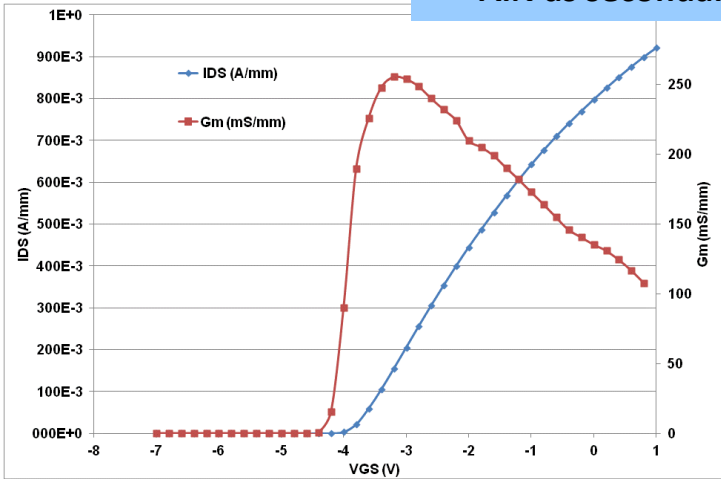
⇒ AlN integration in a real process

Patent: « Dispositif optique utilisant un dépôt de Nitrure d'Aluminium, non épitaxié, assurant une fonction optique »





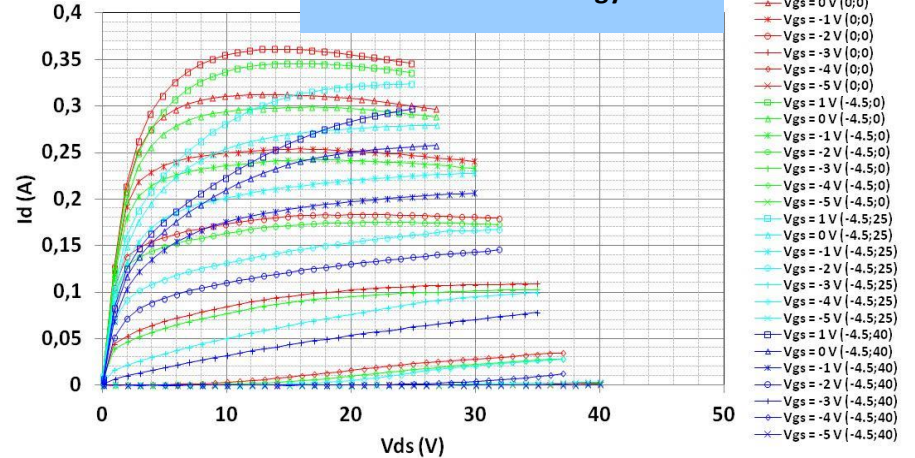
AlN as secondary passivation layer



Good Static and pulsed IV measurements
 $G_m = 250\text{mS/mm}$, $I_{dss} = 880\text{mA/mm}$, $V_p = -4.3\text{V}$

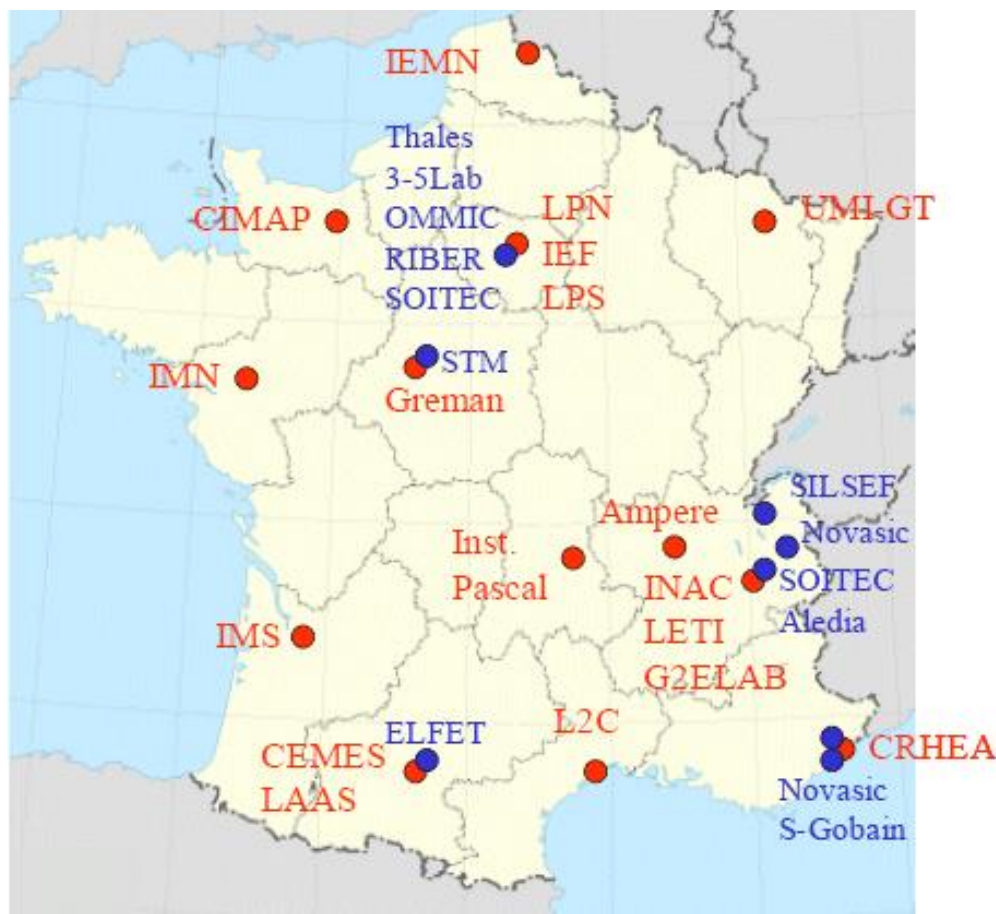
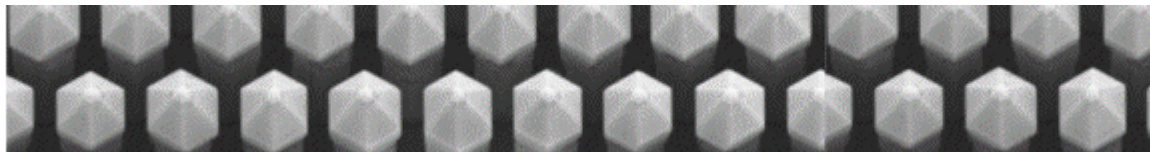
$I_{dss} = 361\text{ mA}$ @ $V_{gs} = 1\text{ V}$
 Gate-lag = 4.4 %
 Drain-lag @ 25 V = 22.6 %
 Drain-lag @ 40 V = 36.1 %

Pulsed IV measurement on HEMT result currently obtained with classical technology



La synergie entre les aspects thermiques et les procédés couches minces fait de l'IMN un partenaire privilégié non seulement pour réduire la température d'élaboration des composants électroniques mais aussi pour assurer leur management thermique.

Participation au Labex Ganex qui est coordonné par le CRHEA et qui rassemble toute la communauté du GaN en France.



❑ Collaboration dans le cadre du Labex Ganex, thèse Ganex et Conseil Régional PdL de Salma Bensalem en collaboration avec l'IEMN à Lille, le CRHEA à Sophia Antipolis et le LAAS à Toulouse (2012-2015).

❑ Collaboration DGA dans le cadre de la thèse de Julien Camus en collaboration avec 3-5 Lab. à Marcoussis (2011-2014).

❑ Thèse CEATech De Sylvain SIM avec le CEA, La Région PdL et ATLANTIC. La thèse est adossée à l'ANR Fichtre en collaboration avec le CEA- LITEN, INP Grenoble et des industriels (Savimes, Polymage, CCIT et Id3) (2013-2016).